



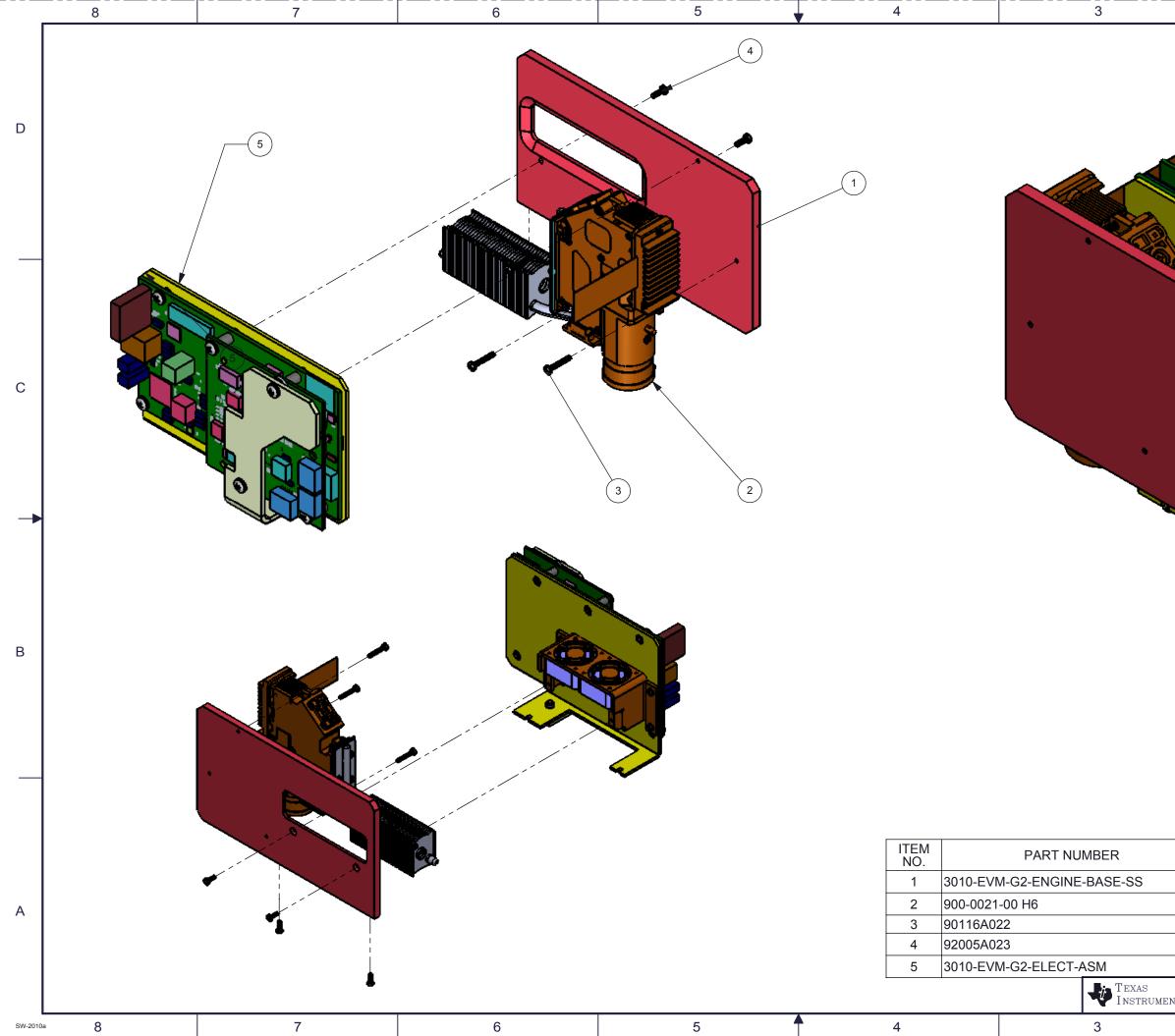
		/G NO 010-EVM-G2-SS-TOP-ASSEMBLY	SHEET	1					
NTS		REVISIONS							
ED	REV	DESCRIPTION		DATE	BY				
	Α	INITIAL RELEASE		1/25/2017	SS				
	В	UPDATED FOR FAN MOUNT CHANGE		2/3/2017	SS				
	С	UPDATED PART DESCRIPTIONS		7/21/2017	SS				

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DWN DATE STEVE SMITH 1/20/2017		T EXAS INSTRUMENTS			А				
Engr STE	VE SMITH	1/27/2017	<u> </u>		•				
CQE/QA		3010 EVM KIT							
СМ									
			SIZE	DWG NO	VM-G	2-SS-TOP-AS	SEMBLY	REV	
Apprvd		B			С				
,			SCALE 1:1 SHEET 1 OF 2		F 2				
		2					1		



	DWG NO 3010-EVM-G2-SS-TOP-ASSEMBLY 2	1		
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			В	
	DESCRIPTION	QTY.		
	ENGINE BASE	1		
	ePROTECH PT3 720P DISPLAY ENGINE	1	А	
	M2 X 12MM LONG PAN HEAD (McMaster-Carr) 3			
	M2 X 6MM LONG PAN HEAD (McMaster-Carr)	4		
	3010 ELECTRONICS ASSEMBLY	1 REV		
INTS	STEVE SMITH 1/20/2017 B 3010-EVM-G2-SS-TOP-ASSEMBL SCALE 1:5 SHEE			
	2	1		

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